



# Material Composition Declaration

## EPC2619

Company Name	Efficient Power Conversion (EPC)	Issue Date:	1/12/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0280	Contact Email:	yanping.ma@epc-co.com
Part Weight:	5.4 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	4.3468	80.7211	83.2030	807211
	Silicon oxide	7631-86-9	0.0186	0.3451		3451
	Silicon nitride	12033-89-5	0.0087	0.1607		1607
	Gallium nitride	25617-97-4	0.0181	0.3355		3355
	Aluminum	7429-90-5	0.0440	0.8168		8168
	Aluminum nitride	24304-00-5	0.0028	0.0516		516
	Titanium	7440-32-6	0.0012	0.0220		220
	Titanium nitride	25583-20-4	0.0058	0.1070		1070
	Copper	7440-50-8	0.0007	0.0136		136
	Tungsten	7440-33-7	0.0014	0.0256		256
	Polyimide		0.0325	0.6041	6041	
Under Bump Metal	Titanium	7440-32-6	0.0007	0.0125	0.1366	125
	Copper	7440-50-8	0.0067	0.1241		1241
Solder Bump	Copper	7440-50-8	0.0669	1.2415	16.6604	12415
	Nickel	7440-02-0	0.0399	0.7406		7406
	Tin	7440-31-5	0.7762	14.4141		144141
	Silver	7440-22-4	0.0142	0.2642		2642
Sum in total:			5.3849	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.